

XFLO® Micro

Low Profile, High Compressive Strength UFH Floorboards



Product Information

XFLO® Micro low profile under floor heating insulation boards have an ultra high compressive strength ideal for domestic and commercial flooring applications. Once covered with **ScreedBoard®** or a floor decking, they provide an effective solution to limited height underfloor heating projects.

Product Benefits

- ⊗ Low profile, as thin as 15mm
- ⊗ Ultra high compressive strength - 500kPa
- ⊗ Manufactured to suit pipe and centres required
- ⊗ Easy to cut to size and install
- ⊗ Works in conjunction with acoustic treatments

Technical Data

		XFLO® Micro
Product description	-	Low profile, ultra high compressive strength, underfloor heating board
Strength at 10% compression	kPa	500
Thermal conductivity	W/mK	0.035
Temperature range	°C	-50/+75
Route sizes available (to suit pipe diameter)	mm	10, 12, 15, 16
Pipe centres	mm	150
Board size	mm	600 x 1200
Thickness'	mm	15, 18, 20, 25

Third Party Accreditation and Approvals



Environmental Credentials

